

■ PRODUCT CHARACTERISTICS

N-Channel	P-Channel
$BV_{DSS} = 30V$	BV_{DSS}
$R_{DS(on)} (Typ@VGS=10V) < 17m\Omega$	$R_{DS(on)}(Typ@VGS= -10V) < 32m$
$R_{DS(on)} (Typ@VGS=4.5V) < 22m\Omega$	$R_{DS(on)}(Typ@VGS=-4.5V)<45.5m$
$I_D=6A$	$I_D=-6A$

■ APPLICATIONS

- * Power management in computing
- * Load switching,quick/wireless charging
- * Motor driving

■ FEATURES

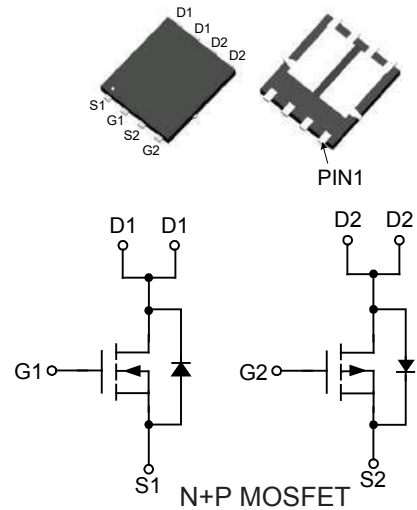
- * Ultra low Rdson
- * Low gate charge
- * Pb-free lead plating

■ ORDER INFORMATION

Order codes		Package	Packing
Halogen- Free	Halogen		
N/A	MOT3650J	PDFN3X3	5000 pieces/Reel

■ ABSOLUTE MAXIMUM RATINGS (T_J=25°C Unless Otherwise Noted)

Parameter	Symbol	Symbol		Unit	
		N-channel	P-channel		
Drain-Source Voltage	V _{DS}	30	-30	V	
Gate-Source Voltage	V _{GS}	±20	±20	V	
Continuous Drain Current	T _A =25°C	I _D	6	-6	A
	T _A =70°C	I _D	5	-5	A
Pulsed Drain Current	I _{DM}	24	-24	A	
Maximum Power Dissipation	P _D	2	2	W	
Thermal Resistance,Junction-to-Ambient	R _{θJA}	62.5	62.5	°C/W	
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	-55 To 150	°C	



-55 To 150

-55 To 150

■ N-ELECTRICAL CHARACTERISTICS (T_c=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.6	3	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =6A	-	17	25	mΩ
		V _{GS} =4.5V, I _D =6A	-	22	30	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =6A	15	-	-	S
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, F=1.0MHz	-	575	-	PF
Output Capacitance	C _{oss}		-	75	-	PF
Reverse Transfer Capacitance	C _{rss}		-	66.5	-	PF
Switching characteristics						
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V, R _L =2.5Ω V _{GS} =10V, R _{GEN} =3Ω	-	4.5	-	nS
Turn-on Rise Time	t _r		-	2.5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	14.5	-	nS
Turn-Off Fall Time	t _f		-	3.5	-	nS
Total Gate Charge	Q _g	V _{DS} =15V, I _D =6A, V _{GS} =10V	-	14.8	-	nC
Gate-Source Charge	Q _{gs}		-	2.6	-	nC
Gate-Drain Charge	Q _{gd}		-	2.9	-	nC
Drain-source diode characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =6A	-	0.8	1.2	V

■ P-ELECTRICAL CHARACTERISTICS (T_c=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.3	-1.65	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-6A	-	32	39	mΩ
		V _{GS} =-4.5V, I _D =-6A	-	45.5	51	mΩ
Forward Transconductance	g _{FS}	V _{DS} =-5V, I _D =-6A	10	-	-	S
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, F=1.0MHz	-	575	-	PF
Output Capacitance	C _{oss}		-	75	-	PF
Reverse Transfer Capacitance	C _{rss}		-	66	-	PF
Switching characteristics						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-15V, R _L =2.5Ω V _{GS} =-10V, R _{GEN} =6Ω	-	7.5	-	nS
Turn-on Rise Time	t _r		-	5.5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	19	-	nS
Turn-Off Fall Time	t _f		-	7	-	nS
Total Gate Charge	Q _g	V _{DS} =-15V, I _D =-6A V _{GS} =-10V	-	11.1	-	nC
Gate-Source Charge	Q _{gs}		-	2.0	-	nC
Gate-Drain Charge	Q _{gd}		-	2.6	-	nC
Drain-source diode characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-6A	-	-	-1.2	V

■ N-TYPICAL CHARACTERISTICS

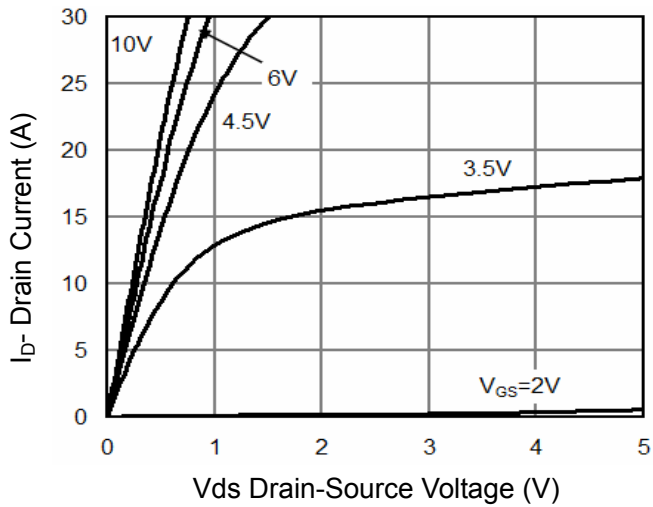


Figure 1:output chattracteristics

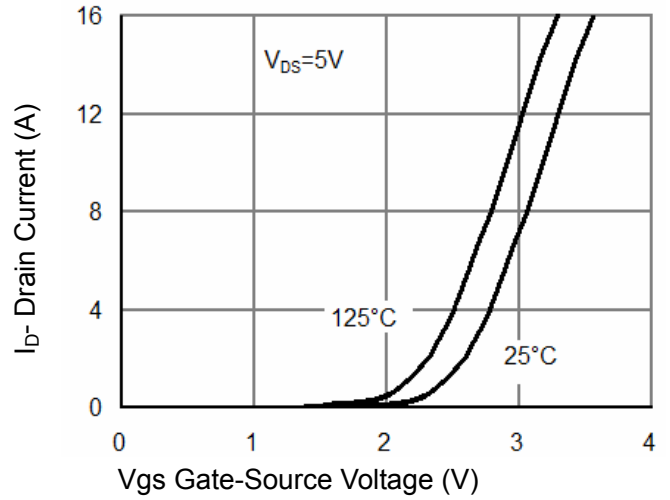


Figure 2:transfer characteristics

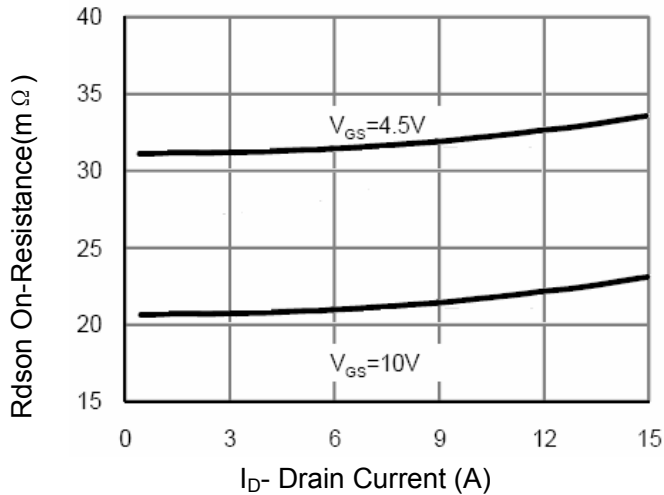


Figure 3:drain-source on-resistance

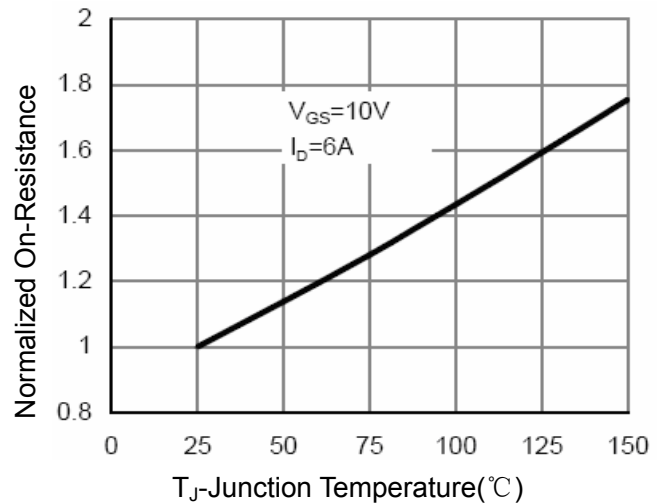


Figure 4:rdson-junction temperature

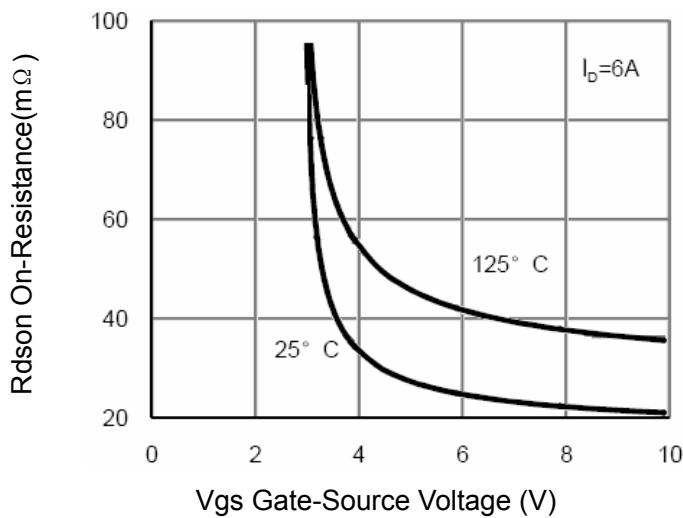


Figure 7:rdson vs vgs

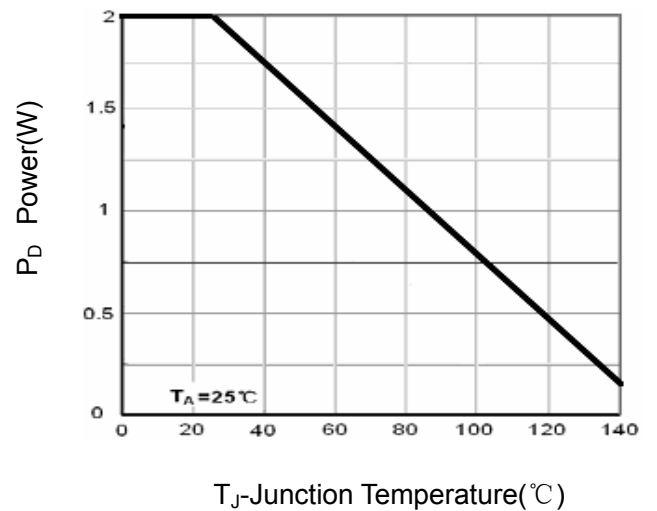


Figure 8:power dissipation

■ N-TYPICAL CHARACTERISTICS(Cont.)

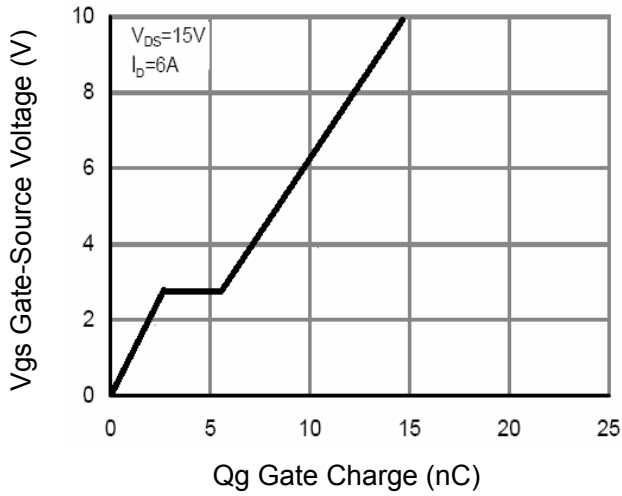


Figure 7:gate charge

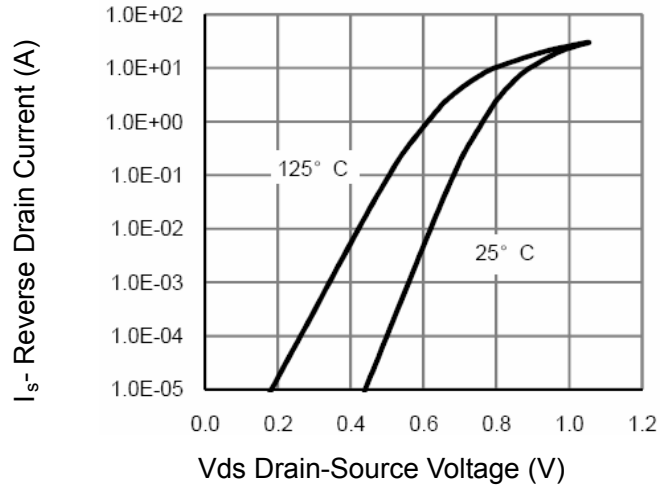


Figure 8:Sourceidrain-diode forward

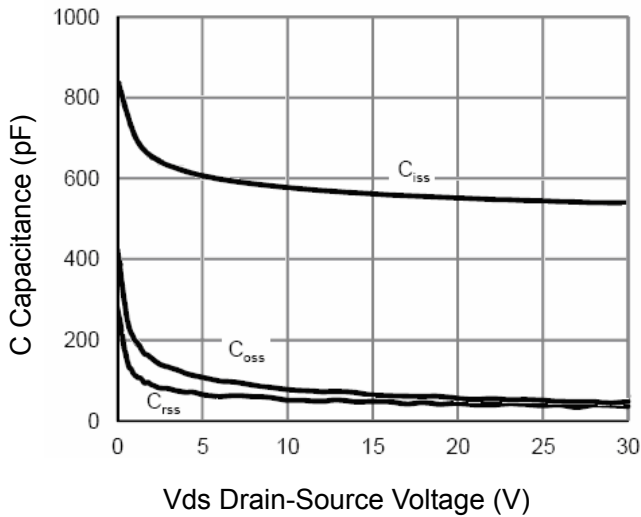


Figure 9:capacitance vs vds

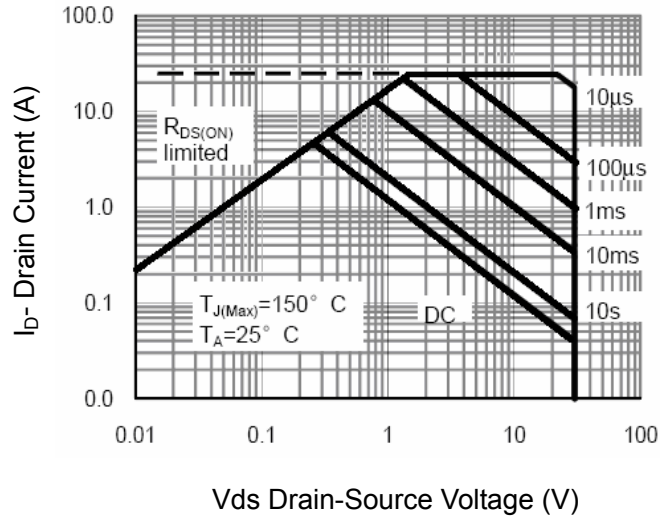


Figure 10:safe operation area

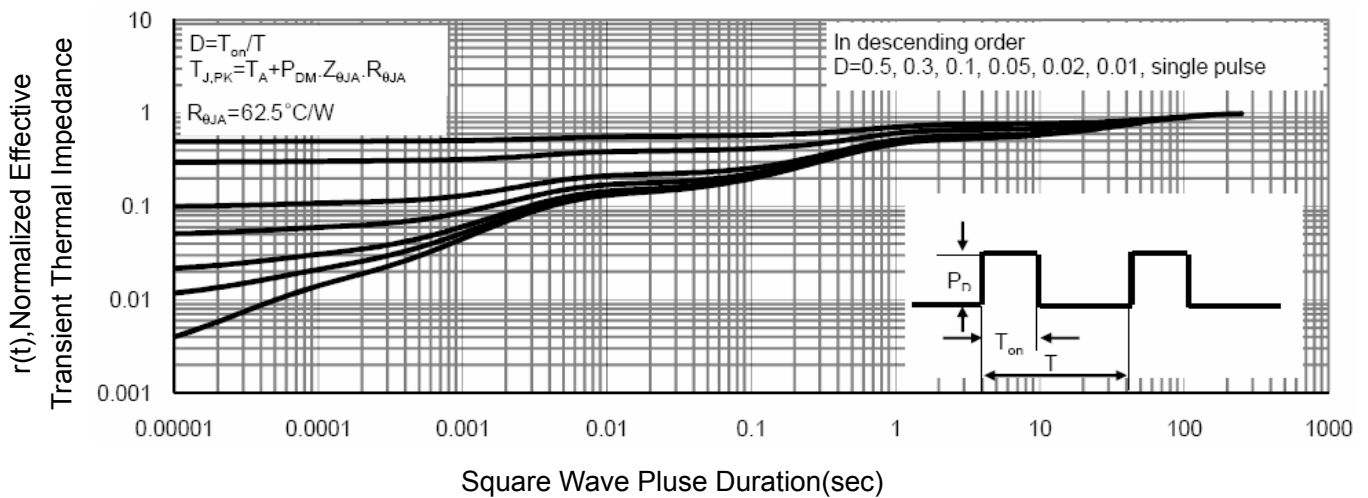


Figure 11: normalized maximum transient thermal impedance

■ P-TYPICAL CHARACTERISTICS

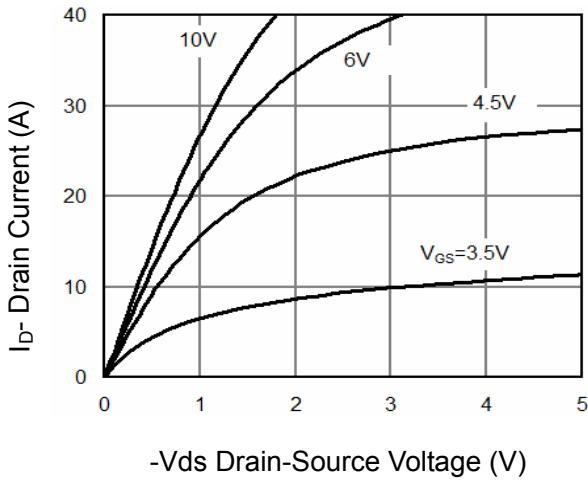


Figure 1: output characteristics

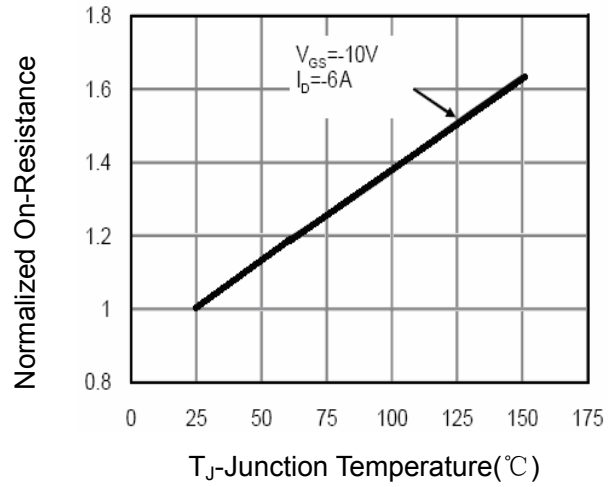


Figure 2: r_{dson} -junction temperature

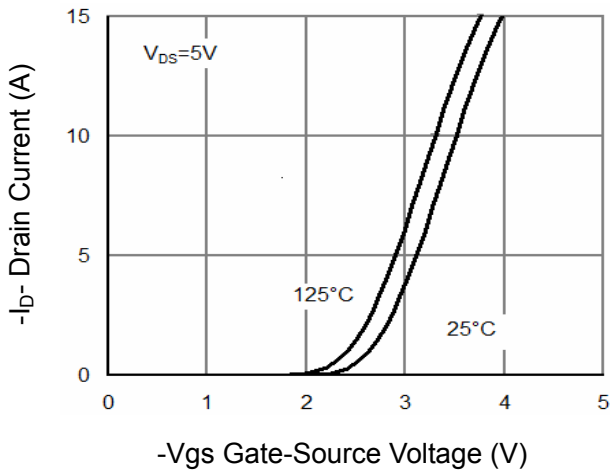


Figure 3: transfer characteristics

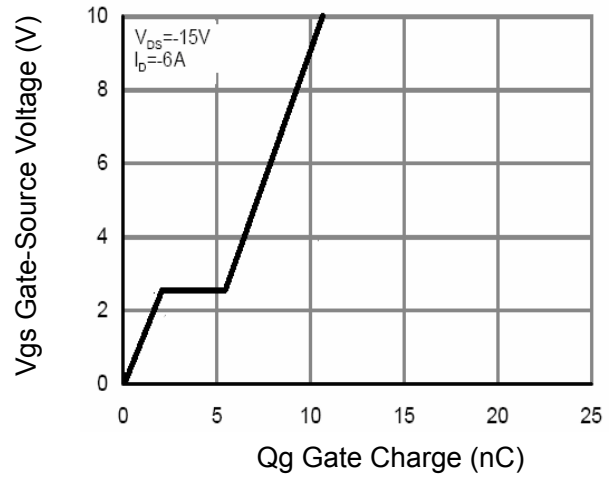


Figure 4: gate charge

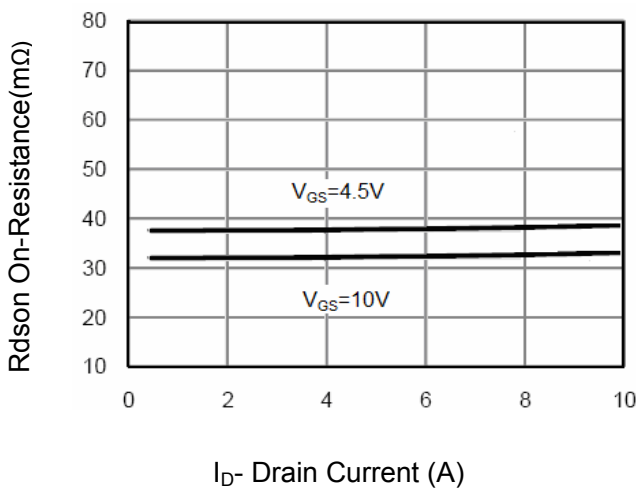


Figure 5: r_{dson} -drain current

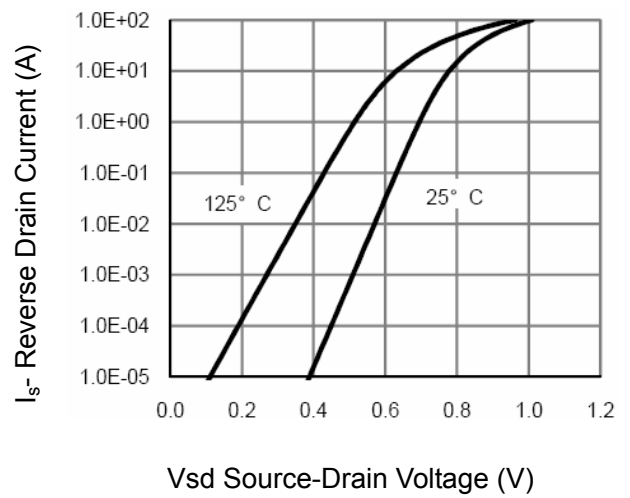


Figure 6: source-drain diode forward

■ P-TYPICAL CHARACTERISTICS(Cont.)

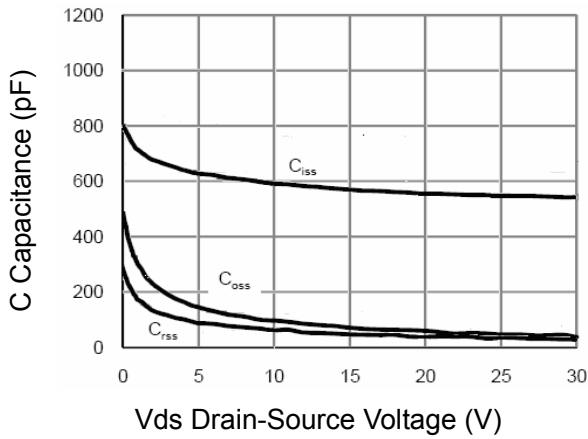


Figure 7:capacitance vs vds

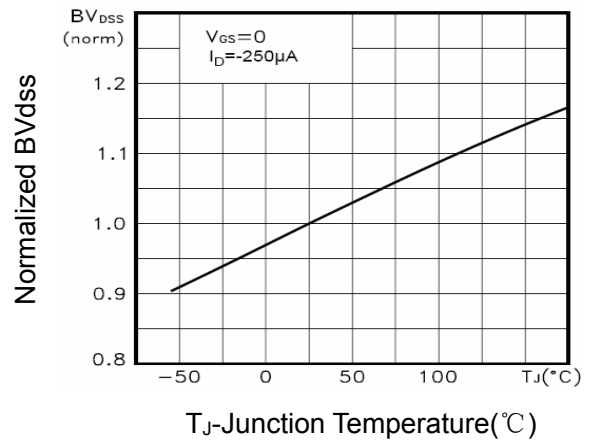


Figure 8:bvdss vs junction temperature

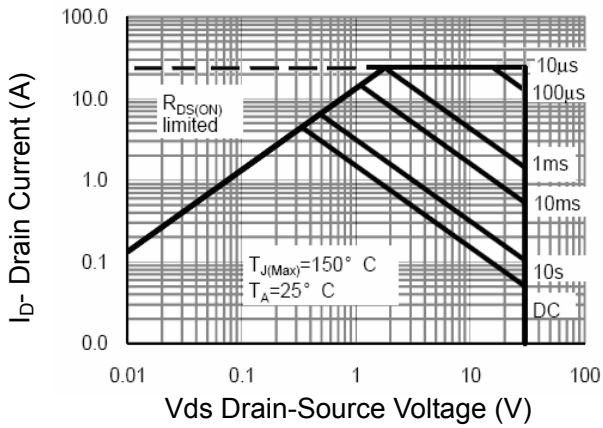


Figure 9:safe operation area

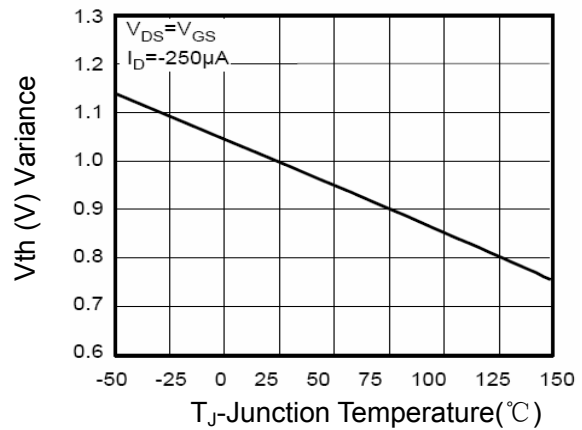


Figure 10:vgs(th) vs junction temperature

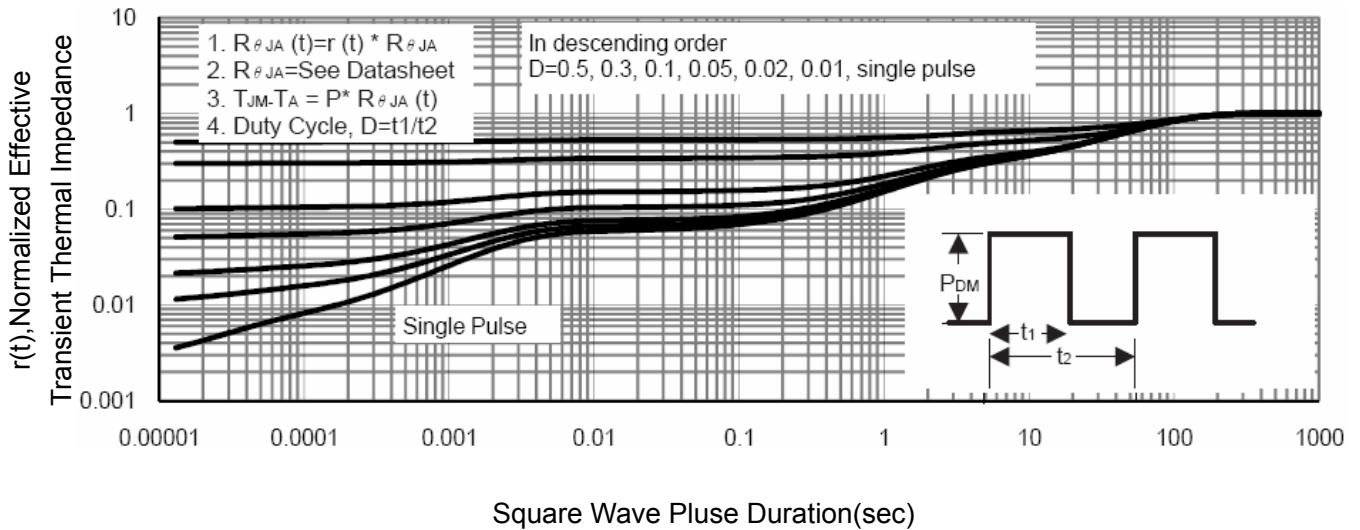


Figure11:normalised maximum transient thermal impedance

■ PDFN3X3-8L Package Mechanical Data

